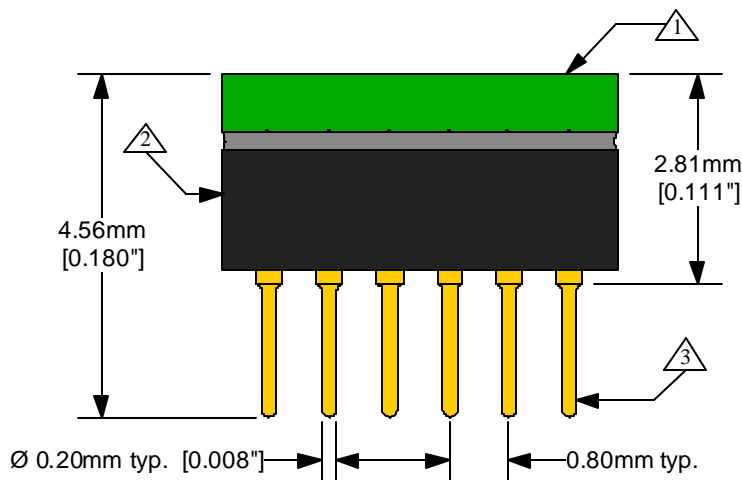


Top View



Side View

- △1 Substrate: 0.79mm ±0.18mm [0.031" ±0.007"]  
FR4/G10 or equivalent high temp material. 17µm [1/2 oz.] Cu clad. SnPb plating.

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- △2 Substrate: 1.59mm ±0.18mm [0.062" ±0.007"]  
FR4/G10 or equivalent high temp material. Non-clad.

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- △3 Pins: shell material- Brass Alloy 360 1/2 hard;  
finish- 0.25µm [10µ"] Au over 1.27µm [50µ"] Ni (min.). Contact material- BeCu; finish 0.25µm [10µ"] Au over 2.54µm [100µ"] Ni (min. ).

**Description:** 32 position MLF land socket  
32 position (+1 Gnd index pin) 0.5mm MLF pattern to 0.8mm pitch UGA male pins.

**Tolerances:** diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

	<b>LS-MLF32A-01 Drawing</b>	Status: Released	Scale: 10:1	Rev: A
	© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com	Drawing: H. Hansen		Date: 11/10/04
		File: LS-MLF32A-01 Dwg	Modified:	